



# AEC-Q100 Qualification Report

Product Series: CA-IF1028XAD-Q1

Report Version: V 1.0

Reference Doc.: AEC-Q100-REV-H

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## 1. Overview

Reliability testing of microelectronic products is a risk mitigation process designed to ensure the service life of device in customer applications. Semiconductor wafer manufacturing process and package-level reliability can be assessed in a variety of ways and may include accelerated environmental test conditions. Chipanalog evaluates manufacturability of the device to verify a robust silicon and assembly flow to ensure continuity of supply to customers. Chipanalog qualifies new devices, significant changes, and product families based on AEC-Q100.

## 2. Part Number List

Package Type	Part Number
DFN8(D)	CA-IF10285AD-Q1/CA-IF10283AD-Q1

**Note:** AECQ-100 provides the guideline for the use of generic data to accelerate and streamline the qualification process. Products sharing the same major product, process and materials elements may be categorized in a product qualification family.

## 3. Production Information

### 3.1. Wafer information

Fab site	SMIC
Wafer	LYRA
Fab Process	18BCDA

### 3.2. Package information

Assembly site	JCET-D3
FT site	JCET-D3
Package	DFN8(D)
Lead Frame	Cu
Bond wire	20um Au
MSL level	MSL1
Operation Temp.	Grade 1(-40°C - 125°C)

## 4. Reliability Qualification Plan

Test Group A-Accelerated Environment Stress Tests					
Group	Item	Refer.	Test condition	QTY	Remark
A1	PC	J-STD-020 JESD22-A113	Test @ Rm, SMD only, Moisture Preconditioning before THB/BHAST, AC/UHAST, TC, and PTC stress, MSL = 1, Peak Reflow Temp = 260°C	240 pcs *0 lots	Use general data of CA-IF10285D-Q1
A2	BHAST	JESD22-A110	BHAST: 130°C, 85% RH, V <sub>cc</sub> = 28V, 96 hrs (Test @ Rm/Hot)	80 pcs *0 lots	Use general data of CA-IF10285D-Q1
A3	UHAST	JESD22-A101	UHAST: 130°C, 85% RH, 96 hrs (Test @ Rm)	80 pcs *0 lots	Use general data of CA-IF10285D-Q1
A4	TC	JESD22-A104	-65°C-150°C, 500 cycles (Test @ Hot)	80 pcs *0 lots	Use general data of CA-IF10285D-Q1
A5	PTC	JESD22-A105	-40°C-125°C, 1000 cycles (Test @ Rm/Hot)	NA	Pd<1W, Δ <40°C
A6	HTSL	JESD22-A103	T <sub>a</sub> = 150°C, 1000 hrs (Test @ Rm/Hot)	45 pcs *0 lot	Use general data of CA-IF10285D-Q1
Test Group B-Accelerated Lifetime Simulation Tests					
Group	Item	Refer.	Test condition	QTY	Remark
B1	HTOL	JESD22-A108	T <sub>a</sub> = 125°C, V <sub>cc</sub> = 28V, 1000 hrs (Test @ Rm/Cold/Hot)	77 pcs*1 lots	Use general data of CA-IF10285AS-Q1
B2	ELFR	AEC-Q100-008	T <sub>a</sub> = 125°C, V <sub>cc</sub> = 28V, 48 hrs (Test @ Rm/Hot)	800 pcs*0 lots	Use general data of CA-IF10285S-Q1
B3	EDR	AEC-Q100-005	Test @ Rm/Hot	NA	No memory device
Group C-Package Assembly Integrity Tests					
Group	Item	Refer.	Test condition	QTY	Remark
C1	WBS	AEC-Q100-001 AEC-Q003	Cpk > 1.67, Each bonder used, T0 samples	30 bonds from 5 pcs	
C2	WBP	MIL-STD883 AEC-Q003	Cpk > 1.67, Each bonder used, T0 samples	30 bonds from 5 pcs	
C2	WBP	MIL-STD883 AEC-Q003	0 fails, Each bonder used, post-TC samples	30 bonds from 5 pcs	
C3	SD	JESD22-B102 JSTD-002D	> 95% coverage, 8hr steam aging prior to testing	15 pcs*1 lot	
C4	PD	JESD22-B100 JESD22-B108 AEC-Q003	Cpk > 1.67	10 pcs*3 lots	
C5	SBS	AEC-Q100-010 AEC-Q003	Cpk > 1.67, 5 balls from min. of 10 devices	NA	No solder ball
C6	LI	JESD22 B105	10 leads from each of 5 devices	NA	No need for SMD device

<b>Test Group D-Die Fabrication Reliability Tests</b>					
<b>Group</b>	<b>Item</b>	<b>Refer.</b>	<b>Test condition</b>	<b>QTY</b>	<b>Remark</b>
D1	EM	JESD61	---	---	Done by Fab
D2	TDDDB	JESD35	---	---	Done by Fab
D3	HCI	JESD60 & 28	---	---	Done by Fab
D4	NBTI	JESD90	---	---	Done by Fab
D5	SM	JESD61, 87, & 202	---	---	Done by Fab
<b>Group E-Electrical Verification Tests</b>					
<b>Group</b>	<b>Item</b>	<b>Refer.</b>	<b>Test condition</b>	<b>QTY</b>	<b>Remark</b>
E1	TEST	per datasheet	Pre and Post Stress Electrical Test	all	
E2	HBM	AEC Q100-002	$\pm 1KV, \pm 2KV$ up to $\pm 8KV$ (Test @ Rm/Hot)	3 pcs*1 lot	
E3	CDM	AEC-Q100-011	$\pm 250V, \pm 500V, \pm 750V, \pm 2KV$ (Test @ Rm/Hot)	3 pcs*1 lot	
E4	LU	AEC-Q100-004	125°C, I-trigger $\pm 100mA$ (Test @ Rm/Hot)	6 pcs*1 lot	
E5	ED	AEC-Q100-009	CPK>1.67	30 pcs*3 lots	
E9	EMC	SAE J1752/3	Electromagnetic Compatibility (Radiated Emissions)	1 pcs*1 lot	
E10	SC	AEC-Q100-012	/	NA	Not 12V smart power device
E11	SER	JESD89-1/-2/-3	/	NA	No memory device
E12	LF	AEC-Q005	/	2 pcs*3 lots	
<b>Group S-Special Requirement Tests</b>					
S1	BLR-Bending	JESD22-B113	Align with customer	NA	
S2	BLR-Drop	JESD22-B11	Align with customer	NA	
S3	BLR-TC	IPC-9701	Refer test requirement	NA	
S4	BLR-Vibration	JESD22-B103	Refer test requirement	NA	

**Note:** Group E6, E7 and Group F are not reliability related items. Group G are not applicable to non-hermetic packaged devices.

## 5. Reliability Test Results

Test Group A-Accelerated Environment Stress Test (DFN8)					
Group	Item	Test Condition	QTY	Lot NO.	Result
A1	PC	Test @ Rm, SMD only, Moisture Preconditioning before BHAST, UHAST, TC stress, MSL = 1, Peak Reflow Temp = 260°C	240 pcs*1 lots	2337B	Pass
A2	BHAST	130°C, 85% RH, 96 hrs, V <sub>cc</sub> = 28V	80 pcs*1 lots	2337B	Pass
A3	UHAST	130°C, 85% RH, 96 hrs	80 pcs*1 lots	2337B	Pass
A4	TC	-65°C-150°C, 500 cycles	80 pcs*1 lots	2337B	Pass
A6	HTSL	T <sub>a</sub> = 150°C, 1000 hrs	45 pcs*1 lot	2337B	Pass
Test Group B-Accelerated Lifetime Simulation Tests					
Group	Item	Test Condition	QTY	Lot NO.	Result
B1	HTOL	T <sub>a</sub> = 125°C, 1000 hrs, V <sub>cc</sub> = 28V, input f = 1kHz, VIH=5.5V, VIL=0V;	77 pcs*4 lots	2329A	Pass
				2230A	Pass
				2331A	Pass
				<b>2503A</b>	<b>Pass</b>
B2	ELFR	T <sub>a</sub> = 125°C, 48 hrs, V <sub>cc</sub> = 28V, input f = 1kHz, VIH=5.5V, VIL=0V;	800 pcs*3 lots	2329A	Pass
				2230A	Pass
				2331A	Pass
Group C-Package Assembly Integrity Tests (DFN8)					
Group	Item	Test Condition	QTY	Lot NO.	Result
C1	WBS	Cpk > 1.67, Each bonder used, T0 samples	30 bonds from 5 pcs	2337B	Cpk=1.678
C2	WBP	Cpk > 1.67, each bonder used, T0 samples	30 bonds from 5 pcs	2337B	Cpk=2.345
C2	WBP	0 fails, Each bonder used, post-TC samples	30 bonds from 5 pcs	2337B	Pass
C3	SD	>95% coverage, 8 hrs steam aging prior to testing	15 pcs*1 lot	2337B	Pass
C4	PD	Per datasheet POD	10 pcs*3 lots	2337B	Pass
				2348B	
				2349B	
TEST GROUP D-Die Fabrication Reliability Tests					
Group	Item	Test Condition	ADDITIONAL REQUIREMENTS		
D1	EM	---	The Die Fabrication Reliability Tests are carried out by every fabrication site. The data, test		
D2	TDDB	---			

D3	HCI	---	method, calculations and internal criteria are available to the customer upon request.		
D4	NBTI	---			
D5	SM	---			
Group E-Electrical Verification Tests					
Group	Item	Test Condition	QTY	Lot NO.	Result
E1	TEST	Pre and Post Stress Electrical Test	all	all	Pass
E2	HBM	$\pm 500V$ , $\pm 1KV$ , $\pm 2KV$ up to $\pm 8KV$ (Test @ Rm/Hot)	3 pcs*1 lot	2503A	3B
E3	CDM	$\pm 250V$ , $\pm 500V$ , $\pm 750V$ , $\pm 2KV$ (Test @ Rm/Hot)	3 pcs*1 lot	2503A	C3
E4	LU	125°C, I-trigger $\pm 100mA$ (Test @ Rm/Hot)t	6 pcs*1 lot	2503A	Class II A
E5	ED	CPK>1.67	30 pcs*3 lots	2337B	Pass
				2348B	
				2349B	
E9	EMC	Electromagnetic Compatibility (Radiated Emissions)	1 pcs*1 lot	2329A	Refer to appendix 1
E12	LF	SOIC8-NB/DFN8	Refer to JCET DFN8 Tin Whisker report		

Note: Group A qualified by 1lot CA-IF10283D-Q1 and 3lots general data of CA-IF1021D-Q1 with same package.

## 6. MTBF&FIT

Supporting Data (Ea = 0.7 eV, Confidence Level = 60%)							MTBF (hrs)	FIT
Test Temp.	Test Voltage	Duration	QTY	Fail QTY	Operation Temp.	Operation Voltage	2.94E+07	33.96
125°C	28V	1000 hrs	231	0	55°C	28V		
125°C	28V	48 hrs	2400	0	55°C	28V		

Note: The FIT data is generated based on Arrhenius model and voltage acceleration model.

## 7. Conclusion

CA-IF1028XAD-Q1 series products are qualified by AEC-Q100 standard.

## Disclaimer

This information is provided to assist customers in design and development. It could change for technology innovation without notice.

The devices are shipped after passing final test. Customers are responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications.

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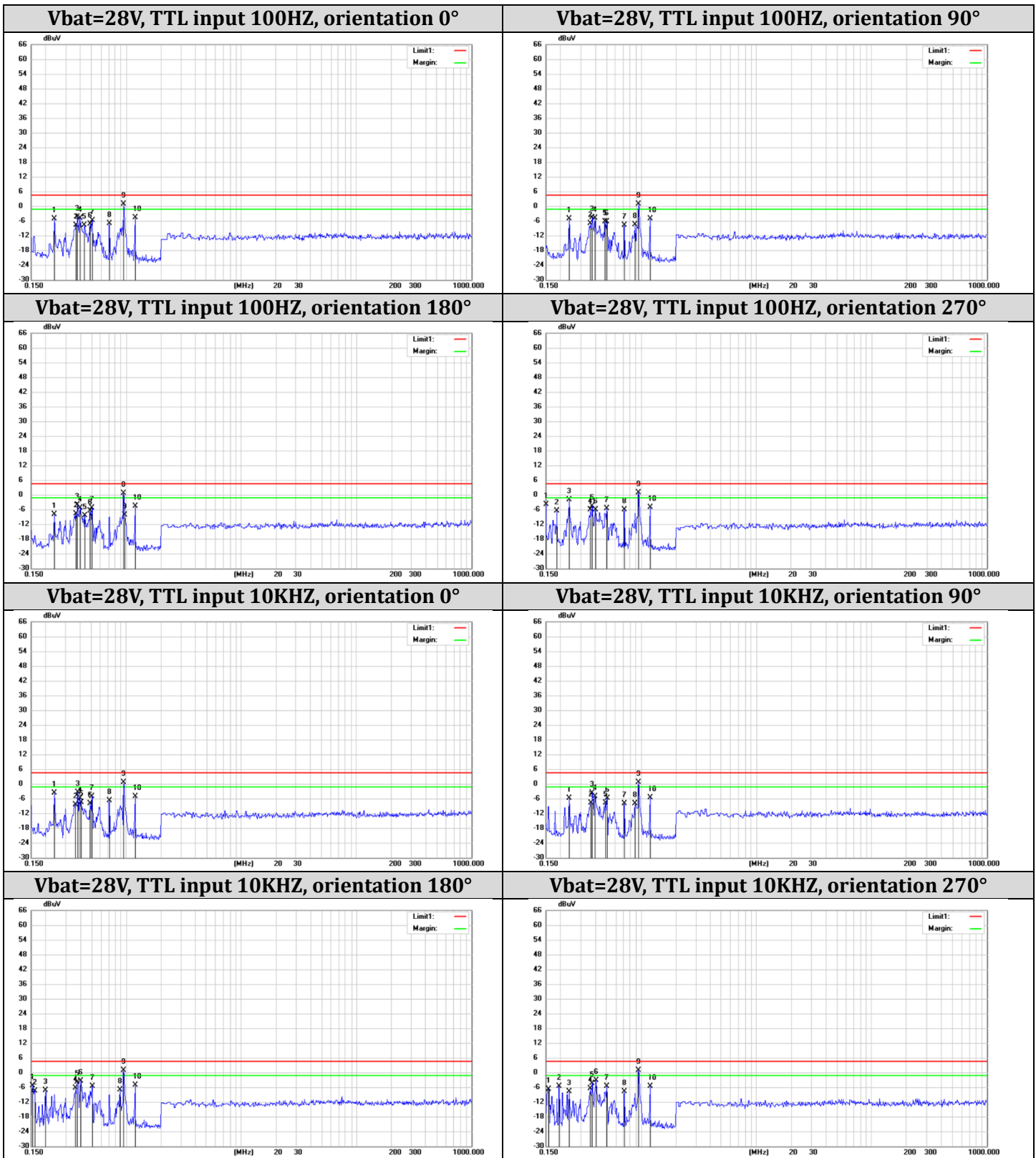
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## Revision History

Revision	Change Log	Date
V1.0	Initial	2025.7.18



# Appendix 1: EMC Test Results



# Appendix 2: SAT Test Results-DFN8

